

IN THE CLAIMS:

The following is a complete listing of the claims, and replaces all earlier listings and all earlier versions.

BEST AVAILABLE

1. (Currently Amended) A solid-state image pickup device comprising:
 - a substrate, provided with no wiring;
 - a solid-state image pickup element chip on which a plurality of solid-state image pickup elements are mounted, said solid-state image device pickup element chip being formed on a light incident side of said substrate;
 - a protection cap provided on a light incident side of said solid-state image pickup element chip and adapted to protect said solid-state image pickup element chip; and
 - a wiring substrate formed of a flexible material and connected electrically to said solid-state image pickup element chip,
 - wherein a connection between said solid-state image pickup element chip and said wiring substrate is fixed only at a bump formed on an electrode pad, and
 - wherein said substrate that is provided with no wiring has a thermal expansion coefficient substantially equal to that of said protection cap, and said substrate that is provided with no wiring and said protection cap are sealed with a sealing resin, so as to form a structure having a hollow space between said solid-state image pickup element chip and said protection cap.

2. - 6. (Cancelled)

7. (Currently Amended) A solid-state image pickup device comprising:

a substrate, provided with no wiring;
a solid-state image pickup element chip on which a plurality of solid-state image pickup elements are mounted, said solid-state image device pickup element chip being formed on a light incident side of said substrate;
a protection cap provided on a light incident side of said solid-state image pickup element chip and adapted to protect said solid-state image pickup element chip; and
a wiring substrate formed of a flexible material and connected electrically to said solid-state image pickup element chip,

wherein a connection between said solid-state image pickup element chip and said wiring substrate is fixed only at a bump formed on an electrode pad, and
wherein said substrate that is provided with no wiring is made of the same material as that of said protection cap, and said substrate that is provided with no wiring and protection cap are sealed with a sealing resin, so as to form a substrate having a hollow space between said solid-state image pickup element chip and said protection cap.

8. - 12. (Cancelled)

13. (Currently Amended) The device according to claim 1, wherein on said protection cap, an optical low pass filter or an infrared infrared rays cut filter is formed.

14. (Previously Added) The device according to claim 1, wherein at a periphery of said protection cap, a light shielding layer is formed.

15. and 16. (Cancelled)

17. (Currently Amended) The device according to claim 1, wherein said solid-state image pickup element chip is adhered onto said substrate that is provided with no wiring, with a flexible adhesive.

18. (Cancelled)

19. (Currently Amended) The device according to claim 1, wherein said substrate that is provided with no wiring, is one of a glass substrate, a ceramic substrate, a metal substrate, a resin substrate, or a substrate formed by stacking two or more of glass, ceramic, metal, and resin substrates.

20. (Previously Added) The device according to claim 1, wherein said sealing resin is a resin selected from the group consisting of epoxy, acrylic, and phenol-based resins.

21. (Currently Amended) The device according to claim 1, further comprising a light-shielding layer, and wherein said solid-state image pickup element chip is formed on said substrate that is provided with no wiring with said light-shielding layer

between said substrate that is provided with no wiring and said solid-state image pickup element chip.

BEST AVAILABLE CC

22. and 23. (Canceled)

24. (Currently Amended) The device according to claim 7, wherein said solid-state image pickup element chip is adhered onto said substrate that is provided with no wiring, with a flexible adhesive.

25. (Canceled)

26. (Currently Amended) The device according to claim 7, wherein the substrate that is provided with no wiring, is one of a glass substrate, a ceramic substrate, a metal substrate, a resin substrate, or a substrate formed by stacking two or more of glass, ceramic, metal, and resin substrates.

27. (Currently Amended) The device according to claim 7, wherein said sealing resin is a resin selected from the group consisting of epoxy, acrylic, and phenol-based resins.

28. (Currently Amended) The device according to claim 7, further comprising a light-shielding layer, and wherein said solid-state image pickup element chip

is formed on said substrate that is provided with no wiring with said light-shielding layer between said substrate and said solid-state image pickup element chip.

BEST AVAILABLE

Cont
C

29. (Previously Added) The device according to claim 7, wherein said light-shielding layer is formed of a light shielding and flexible adhesive.